

3SK297

Silicon N-Channel Dual Gate MOS FET

REJ03G0816-0300 (Previous ADE-208-389A) Rev.3.00 Aug.10.2005

Application

UHF / VHF RF amplifier

Features

- Low noise figure. NF = 1.0 dB typ. at f = 200 MHz
- Capable of low voltage operation

Outline

RENESAS Package code: PLSP0004ZA-A (Package name: MPAK-4)

3

- 1. Source
- 2. Gate1
- 3. Gate2
- 4. Drain

Note: Marking is "ZP-"

Attention:

This device is very sensitive to electro static discharge.

It is recommended to adopt appropriate cautions when handling this transistor.

Absolute Maximum Ratings

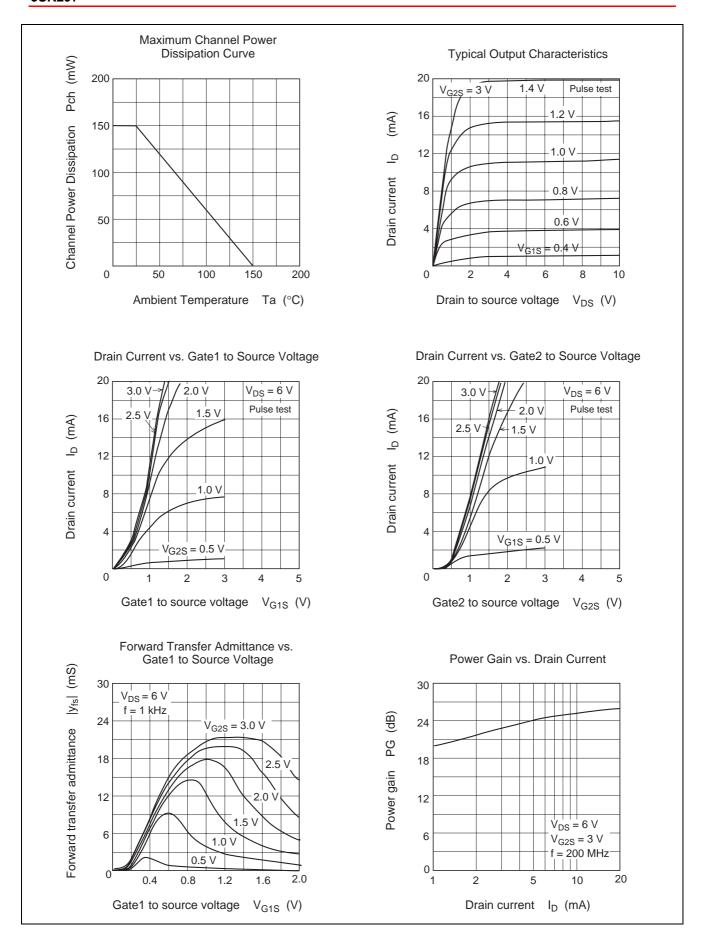
 $(Ta = 25^{\circ}C)$

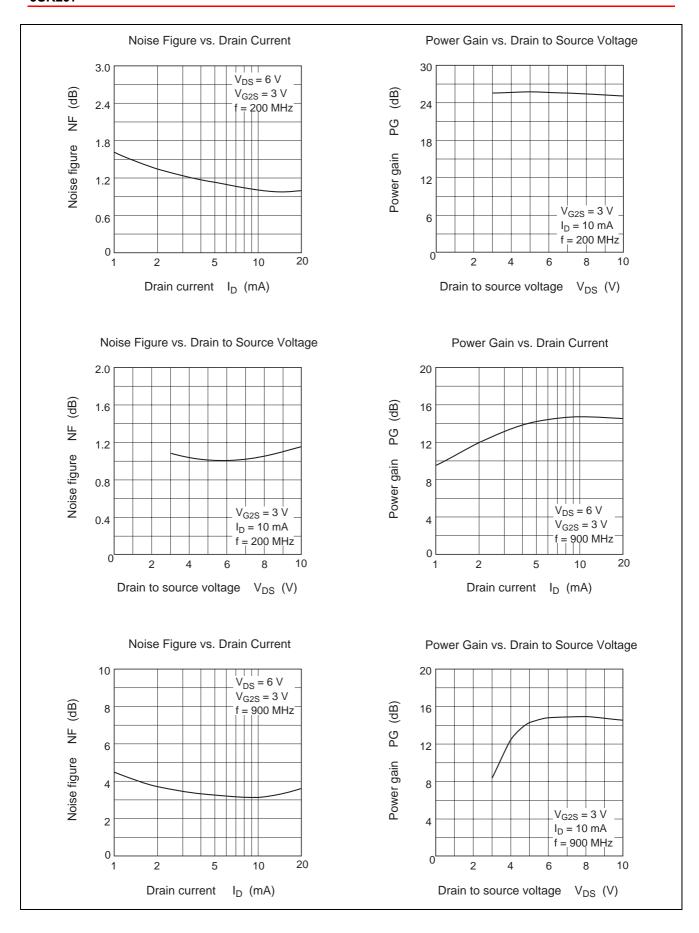
| Item | Symbol | Ratings | Unit |
|---------------------------|----------------|-------------|------|
| Drain to source voltage | V_{DS} | 12 | V |
| Gate 1 to source voltage | V_{G1S} | ±8 | V |
| Gate 2 to source voltage | V_{G2S} | ±8 | V |
| Drain current | I _D | 25 | mA |
| Channel power dissipation | Pch | 150 | mW |
| Channel temperature | Tch | 150 | °C |
| Storage temperature | Tstg | -55 to +150 | °C |

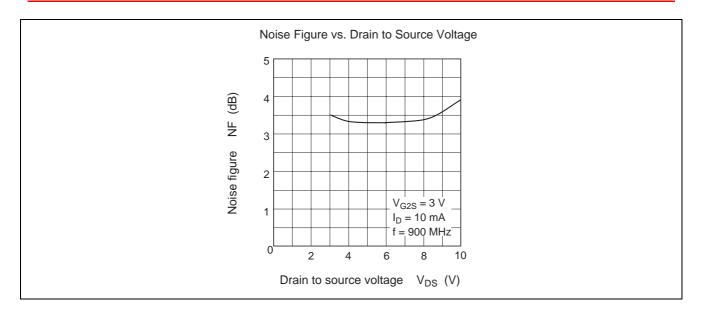
Electrical Characteristics

 $(Ta = 25^{\circ}C)$

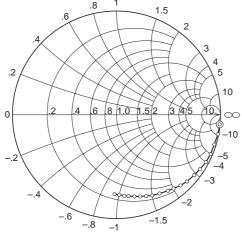
| Item | Symbol | Min | Тур | Max | Unit | Test conditions |
|------------------------------------|---------------------|-----|-------|------|------|---|
| Drain to source breakdown voltage | $V_{(BR)DSX}$ | 12 | _ | _ | V | $I_D = 200 \ \mu A$, $V_{G1S} = -3 \ V$, |
| | | | | | | $V_{G2S} = -3 V$ |
| Gate 1 to source breakdown voltage | $V_{(BR)G1SS}$ | ±8 | | | V | $I_{G1} = \pm 10 \mu A, V_{G2S} = V_{DS} = 0$ |
| Gate 2 to source breakdown voltage | $V_{(BR) G2SS}$ | ±8 | _ | | V | $I_{G2} = \pm 10 \mu A, V_{G1S} = V_{DS} = 0$ |
| Gate 1 cutoff current | I _{G1SS} | _ | _ | ±100 | nA | $V_{G1S} = \pm 6 \text{ V}, V_{G2S} = V_{DS} = 0$ |
| Gate 2 cutoff current | I_{G2SS} | _ | _ | ±100 | nA | $V_{G2S} = \pm 6 \text{ V}, V_{G1S} = V_{DS} = 0$ |
| Drain current | I _{DS(on)} | 0.5 | _ | 10 | mA | $V_{DS} = 6 \text{ V}, V_{G1S} = 0.75 \text{ V},$ |
| | | | | | | V _{G2S} = 3 V |
| Gate 1 to source cutoff voltage | $V_{G1S(off)}$ | 0 | _ | +1.0 | V | $V_{DS} = 10 \text{ V}, V_{G2S} = 3 \text{ V},$ |
| | | | | | | I _D = 100 μA |
| Gate 2 to source cutoff voltage | $V_{G2S(off)}$ | 0 | _ | +1.0 | V | $V_{DS} = 10 \text{ V}, V_{G1S} = 3 \text{ V},$ |
| | | | | | | I _D = 100 μA |
| Forward transfer admittance | y _{fs} | 16 | 20 | _ | mS | $V_{DS} = 6 \text{ V}, V_{G2S} = 3 \text{ V},$ |
| | | | | | | $I_D = 10 \text{ mA}, f = 1 \text{ kHz}$ |
| Input capacitance | Ciss | 2.4 | 2.9 | 3.4 | pF | $V_{DS} = 6 \text{ V}, V_{G2S} = 3 \text{ V},$ |
| Output capacitance | Coss | 8.0 | 1.0 | 1.4 | pF | I _D = 10 mA, f = 1 MHz |
| Reverse transfer capacitance | Crss | | 0.023 | 0.04 | pF | |
| Power gain | PG | 22 | 25 | | dB | $V_{DS} = 6 \text{ V}, V_{G2S} = 3 \text{V},$ |
| Noise figure | NF | _ | 1.0 | 1.8 | dB | I _D = 10 mA, f = 200 MHz |
| Power gain | PG | 12 | 15 | | dB | V _{DS} = 6 V, V _{G2S} = 3 V, |
| Noise figure | NF | _ | 3.2 | 4.5 | dB | I _D = 10 mA, f = 900 MHz |
| Noise figure | NF | _ | 2.8 | 3.5 | dB | $V_{DS} = 6 \text{ V}, V_{G2S} = 3 \text{ V},$ |
| | | | | | | I _D = 10 mA, f = 60 MHz |







S11 Parameter vs. Frequency



Condition: $V_{DS} = 6 \text{ V}$, $V_{G2S} = 3 \text{ V}$ $I_{D} = 10 \text{ mA}$, $Zo = 50\Omega$ 50 to 1000 MHz (50 MHz step)

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150°

S21 Parameter vs. Frequency

Scale: 0.5 / div.

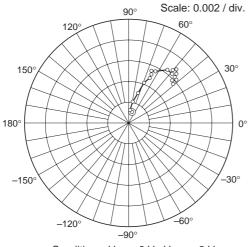
-30°

Condition: $V_{DS} = 6 \text{ V}$, $V_{G2S} = 3 \text{ V}$ $I_D = 10 \text{ mA}$, $Zo = 50\Omega$ 50 to 1000 MHz (50 MHz step)

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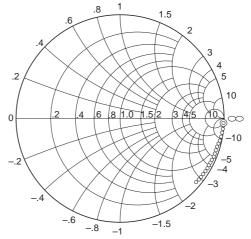
-120°

S12 Parameter vs. Frequency



 $\begin{array}{ll} \text{Condition:} & \text{V}_{DS} = 6 \text{ V} \text{ , V}_{G2S} = 3 \text{ V} \\ & \text{I}_{D} = 10 \text{ mA} \text{ , Zo} = 50\Omega \\ \\ \text{50 to 1000 MHz (50 MHz step)} \\ \end{array}$

S22 Parameter vs. Frequency



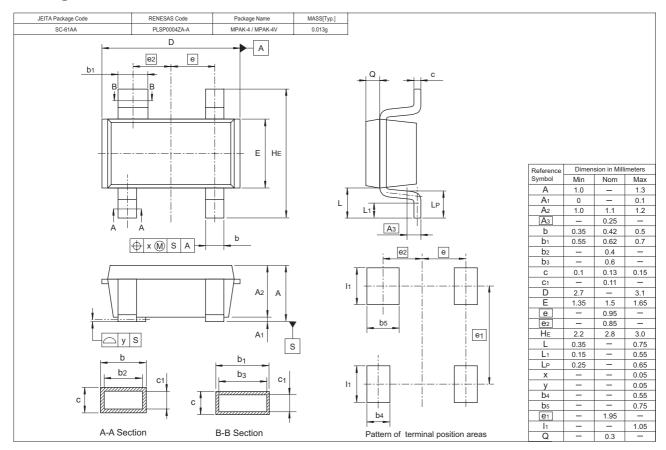
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S Parameter

 $(V_{DS} = 6 \text{ V}, V_{G2S} = 3 \text{ V}, I_D = 10 \text{ mA}, Z_O = 50 \Omega)$

| Freq. | S | 11 | S | 21 | S12 | | S22 | | |
|-------|-------|---------------|------|-------|---------|------|-------|-------|--|
| (MHz) | MAG. | ANG. | MAG. | ANG. | MAG. | ANG. | MAG. | ANG. | |
| 50 | 0.994 | -5.8 | 2.04 | 173.6 | 0.00116 | 76.9 | 0.993 | -2.2 | |
| 100 | 0.993 | -11.0 | 2.02 | 167.4 | 0.00132 | 85.7 | 0.993 | -4.5 | |
| 150 | 0.986 | -16.8 | 2.00 | 161.5 | 0.00229 | 78.2 | 0.991 | -6.4 | |
| 200 | 0.980 | -22.5 | 1.98 | 155.5 | 0.00313 | 73.5 | 0.990 | -8.5 | |
| 250 | 0.973 | -27.8 | 1.94 | 149.6 | 0.00427 | 68.7 | 0.987 | -10.5 | |
| 300 | 0.950 | -33.0 | 1.90 | 142.6 | 0.00473 | 63.9 | 0.985 | -12.5 | |
| 350 | 0.936 | -38.3 | 1.86 | 137.1 | 0.00536 | 64.3 | 0.982 | -14.4 | |
| 400 | 0.924 | -43.4 | 1.83 | 131.6 | 0.00561 | 64.5 | 0.979 | -16.2 | |
| 450 | 0.912 | -48.0 | 1.77 | 126.8 | 0.00562 | 60.9 | 0.975 | -18.2 | |
| 500 | 0.893 | -52.5 | 1.71 | 121.0 | 0.00640 | 53.5 | 0.971 | -20.2 | |
| 550 | 0.874 | - 57.3 | 1.67 | 115.5 | 0.00638 | 49.3 | 0.967 | -22.0 | |
| 600 | 0.859 | -62.0 | 1.64 | 111.1 | 0.00647 | 49.0 | 0.964 | -23.9 | |
| 650 | 0.846 | – 66.1 | 1.58 | 106.7 | 0.00667 | 50.2 | 0.960 | -25.8 | |
| 700 | 0.829 | -69.8 | 1.50 | 102.1 | 0.00694 | 49.3 | 0.955 | -27.6 | |
| 750 | 0.810 | -74.2 | 1.46 | 97.1 | 0.00661 | 46.6 | 0.952 | -29.4 | |
| 800 | 0.802 | -78.0 | 1.44 | 92.7 | 0.00618 | 43.7 | 0.948 | -31.2 | |
| 850 | 0.791 | -81.6 | 1.38 | 88.9 | 0.00622 | 44.7 | 0.944 | -33.2 | |
| 900 | 0.778 | -84.6 | 1.34 | 84.2 | 0.00615 | 43.6 | 0.940 | -35.1 | |
| 950 | 0.756 | -88.5 | 1.30 | 80.2 | 0.00576 | 45.1 | 0.935 | -36.8 | |
| 1000 | 0.751 | -92.2 | 1.26 | 75.9 | 0.00562 | 40.7 | 0.932 | -38.5 | |

Package Dimensions



Ordering Information

| Part Name | Quantity | Shipping Container |
|---------------|----------|-----------------------------------|
| 3SK297ZP-TL-E | 3000 | φ 178 mm Reel, 8 mm Emboss Taping |

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